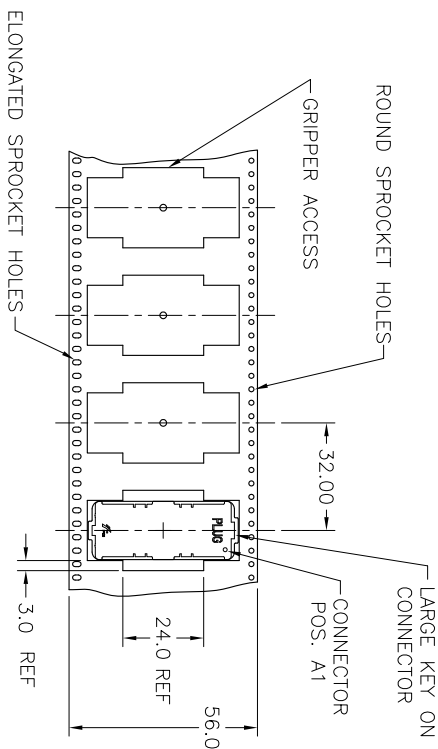
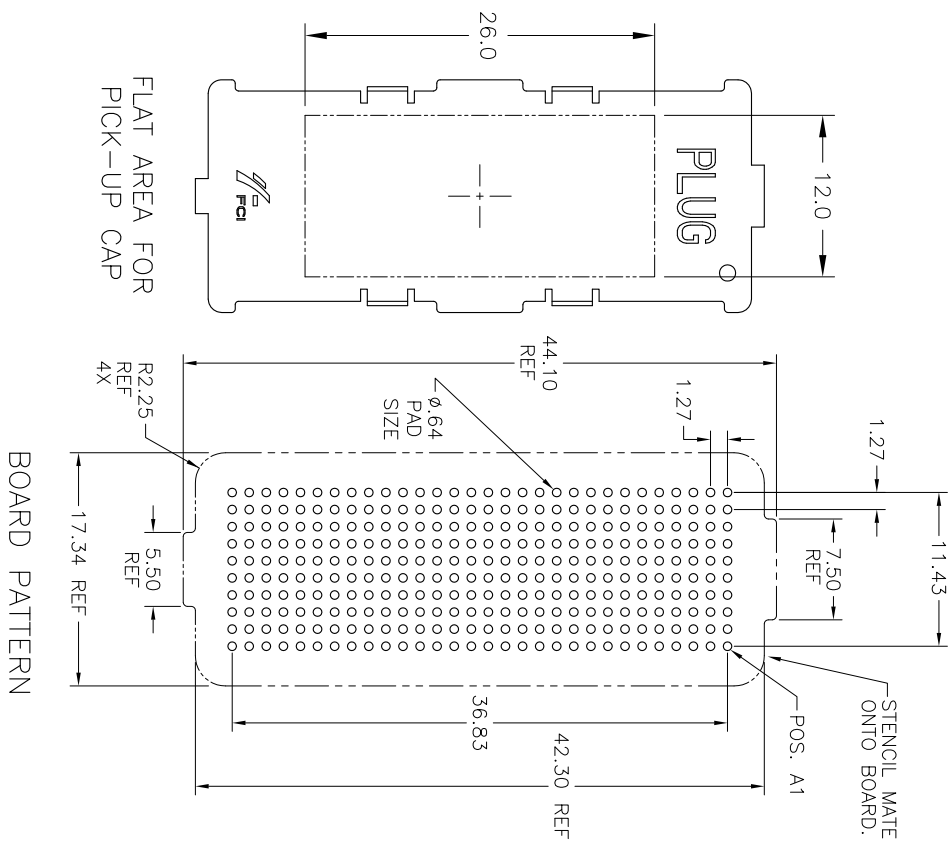


4

mat'l. code		surface		tolerance		projection		product family	
SEE NOTE 1.		ASME Y14.5		ASME Y14.5				MEG-ARRAY	
lth	ecn no	df	date	tolerances unless otherwise specified				title	
A	V05-0324	DAI	2005/04/19	X*3		MM		0mm PLUG ASSY	
B	V06-0560	LP	2006/07/18	XX*3				10 X 30 = 300 POS.	
C	V08-0084	LP	2008/03/07	XX*051		scale 3:1			
D	V-13789	DCH	2012/11/23	D.INGRAM				dwg no	
				D.HARPER				sheet 1 of 3	
				D.HARPER				10043343	
				D.HARPER				A4	
sheet	revision	D	D	D.HARPER				type	
index	sheet	1	2	D.HARPER				CUSTOMER Drawing	



PRODUCT NUMBER
SEE TABLE



TAPE & REEL PACKAGING SCALE: NONE
PER EIA 481-3

CONFIDENTIAL

mat'l. code		surface		tolerance		projection		product family	
SEE NOTE 1.		ASME Y14.5		ASME Y14.5				MEG--ARRAY	
ltr	ecn no	dr	date	tolerances unless otherwise specified				title	
D				angles X*3 XX*3 XXX*051		MM scale 2:1		0mm PLUG ASSY 10 X 30 = 300 POS.	
				dr D:INGRAM 7/21/04 ENG'R D:HARPER 7/21/04 chn D:HARPER 7/21/04 app'd D:HARPER 7/21/04		dwg no 10043343		sheet 2 of A4	
sheet revision								CUSTOMER Drawing	
index	sheet								



PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
10043343-102	YES	30u"(0.76um) Au OVER Ni	SnPb
10043343-102LF			SnAgCu LEAD FREE ⑥⑦
10043343-192			SnPb
10043343-192LF	YES	30u"(0.76um) GXT OVER Ni	SnAgCu LEAD FREE ⑥⑦
10043343-202			SnPb
10043343-202LF			SnAgCu LEAD FREE ⑥⑦
10043343-292	YES	50u"(1.27um) Au SPECIAL	SnPb
10043343-292LF			SnAgCu LEAD FREE ⑥⑦

NOTES:

①. MAT'L:

HOUSING: LCP

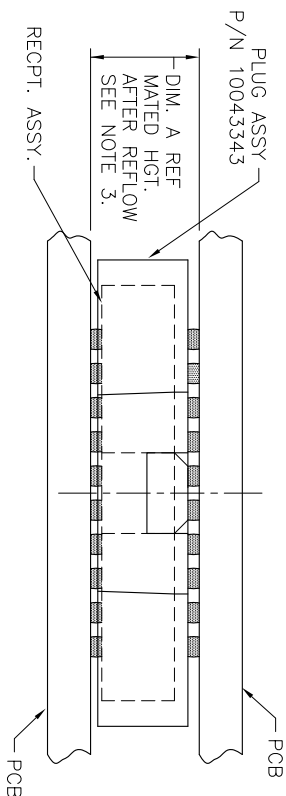
CONTACT: COPPER ALLOY

PLATING:

CONTACT: (SEE TABLE ON SHEET3)
SOLDER BALL: (SEE TABLE ON SHEET3)
EUTECTIC SnPb OR LEAD FREE
95.5Sn /4Ag/0.5Cu

2. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE DUE TO REFLOW ATTACHMENT.
3. MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE, PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.
4. PLATING FOR INDICATED -2XX SERIES PART NOS. MEETS THE REQUIREMENTS OF CENTRAL OFFICE ENVIRONMENT (25 YEAR LIFE EXPECTANCY).
5. PLATING FOR INDICATED -2XX SERIES PART NOS. IS Au OR GXT OVER Ni WITH SPECIAL CONTACT GEOMETRY TO MEET REQUIREMENTS OF TELCORDIA GR-1217-CORE: CENTRAL OFFICE ENVIRONMENT.

- ⑥ FOR PROPER APPLICATION FOLLOW FCI APPLICATION SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE FCI APPLICATION SPECIFICATION
- ⑦ THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT CODE NUMBER MARKED ON EACH PART BY HAVING AN "X" IN THE SEVENTH CHARACTER POSITION
- ⑧ KNIT LINE: SLIGHT VISIBLE MARKS (USUALLY A LINE) THE DIRECTION AND MEETING POINT OF THE PLASTIC RESIN FLOW FRONTS TRAVELING AROUND ANY OBSTRUCTIONS TO THE RESIN FLOW VIA THE REQUIRED MOLD TOOLING.



MATED HEIGHT TABLE	
DIM. A	RECPT. ASSY. P/N
4.0	84501 SEE NOTE 4.
5.5	84502 *
8.0	84553 SEE NOTE 5.

* 84502 NOT AVAILABLE IN TELCORDIA/NORTEL VERSION.

MATED HEIGHT AFTER REFLOW IS BASED ON Ø .64mm PAD (METAL-DEFINED) AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW - MATED CONNECTORS SCALE: NONE

mat'l. code		surface		tolerance		projection		product family	
SEE NOTE 1.		ASME Y14.5		ASME Y14.5				MEG-ARRAY	
lfr	ecn no	dr	date	tolerances unless otherwise specified				title	
D				angles				0mm PLUG ASSY	
								10 X 30 = 300 POS.	
								dwg no	
								sheet 3 of	
								size	
								10043343	
								A4	
								CUSTOMER Drawing	
sheet	revision								
index	sheet								